


MATERIAL DECLARATION SHEET



Material Number	SM42002EL			
Product Line	LAN Transformer Module			
Compliance Date	2020/07/16			
RoHS Compliant	Yes	MSL	Level 1	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [g]	Homogeneous Material Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	PCB	Cupreous clad laminate	0.38402	Copper	7440-50-8	53.000	12.3129600	23.23200
				GLASS FABRIC	65997-17-3	40.000	9.2928000	
				Epoxy Resin	61788-97-4	7.000	1.6262400	
		Marking-Black Ink	0.01480	Epoxy	9003-36-5	50.556	0.4526784	0.89540
				Barium sulfate	7727-43-7	30.334	0.2716106	
				Carbon Black	1333-86-4	10.111	0.0905339	
				Silicon Dioxide	14464-46-1	5.056	0.0452714	
				Dimethylpolysiloxane	63148-62-9	1.517	0.0135832	
				2-Isopropylthioxanthone	5495-84-1	1.011	0.0090525	
				2-Methyl-4'-(methylthio)-2-morpholinopropiophenone	71868-10-5	1.011	0.0090525	
				Melamine	108-78-1	0.303	0.0027131	
				Dipropylene Glycol Methyl Ether	34590-94-8	0.101	0.0009044	
				Marking-White Ink	0.00080	POLY[(O-CRESYL GLYCIDYL ETHER)-CO-FORMALDEHYDE]	29690-82-2	
		BISPHENOL A DIGLYCIDYL ETHER RESIN	25068-38-6			22.222	0.0107554	
		Silicon Dioxide	14464-46-1			11.111	0.0053777	
		Titanium (IV) Oxide	13463-67-7			33.333	0.0161332	
		Dicyandiamide	461-58-5			5.556	0.0026891	
		Plating-Ni	0.00028	Nickel	7440-02-0	100.000	0.0169400	0.01694
Plating-Au	0.00012							

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2	Common Mode Choke Coil x 4	Ferrite body	0.03691	Iron oxide	1309-37-1	62.000	1.3844600	2.23300
				Nickel oxide	1313-99-1	11.000	0.2456300	
				Zinc oxide	1314-13-2	20.000	0.4466000	
				Copper oxide	1317-38-0	7.000	0.1563100	
		Copper/ Coating	0.00575	Copper	7440-50-8	100.000	0.3480000	0.43500
				0.00144	Polyurethane Resin	26680-22-8	100.000	
		Terminal	0.00144	Silver	7440-22-4	73.700	0.0641190	0.08700
				Silicon dioxide	60676-86-0	15.800	0.0137460	
				Resins	9004-57-3	10.500	0.0091350	
		Solder Base	0.00048	Nickel	7440-02-0	100.000	0.0290000	0.02900
		Solder	0.00048	Tin	7440-31-5	100.000	0.0290000	0.02900
		Adhesive	0.00144	Epoxy resin	61788-97-4	50.000	0.0435000	0.08700
				Carbon black	1333-86-4	46.000	0.0400200	
Acrylated Aliphatic Urethane	68987-79-1			4.000	0.0034800			
3	SMD Pulse Transformer x 4	Ferrite body	0.51502	Iron oxide	1309-37-1	62.000	19.3171230	31.15665
				Nickel oxide	1313-99-1	11.000	3.4272315	
				Zinc oxide	1314-13-2	20.000	6.2313300	
				Copper oxide	1317-38-0	7.000	2.1809655	
		Copper	0.07873	Copper	7440-50-8	100.000	4.7628000	5.95350
		Coating	0.01968	Polyurethane Resin	26680-22-8	100.000	1.1907000	
		Terminal	0.01640	Silver	7440-22-4	73.700	0.7312883	0.99225
				Silicon dioxide	60676-86-0	15.800	0.1567755	
				Resins	9004-57-3	10.500	0.1041863	
		Solder Base	0.00328	Nickel	7440-02-0	100.000	0.1984500	0.19845
		Solder	0.00328	Tin	7440-31-5	100.000	0.1984500	0.19845
		Adhesive	0.01968	Epoxy resin	61788-97-4	50.000	0.5953500	1.19070
				Carbon black	1333-86-4	46.000	0.5477220	
Acrylated Aliphatic Urethane	68987-79-1			4.000	0.0476280			

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4	Iron shell	STAINLESS STEEL STRIP	0.48677	Stainless steel	12597-68-1	100.000	29.4474700	31.03000
		Plating-Ni	0.02616	Nickel	7440-02-0	100.000	1.5825300	
5	Solder Paste	Solder	0.03604	Tin	7440-31-5	98.500	2.1473000	2.18000
				Silver	7440-22-4	1.000	0.0218000	
				Copper	7440-50-8	0.500	0.0109000	
		Total weight	1.653					

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Important remarks:

1. It is the responsibility of the user to verify they are accessing the latest version.
sheet picture.